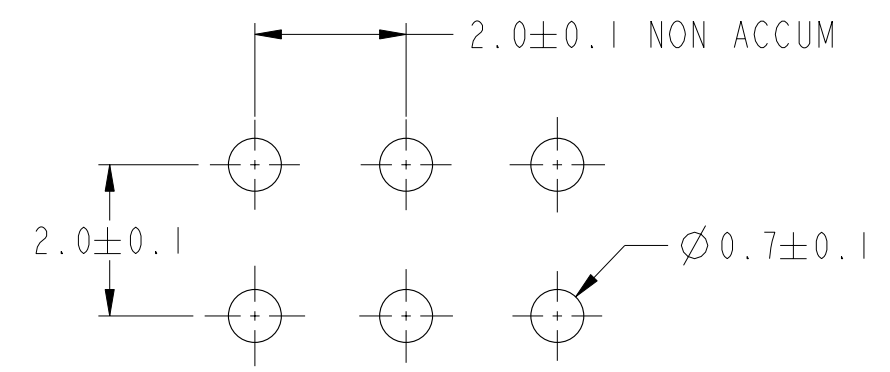
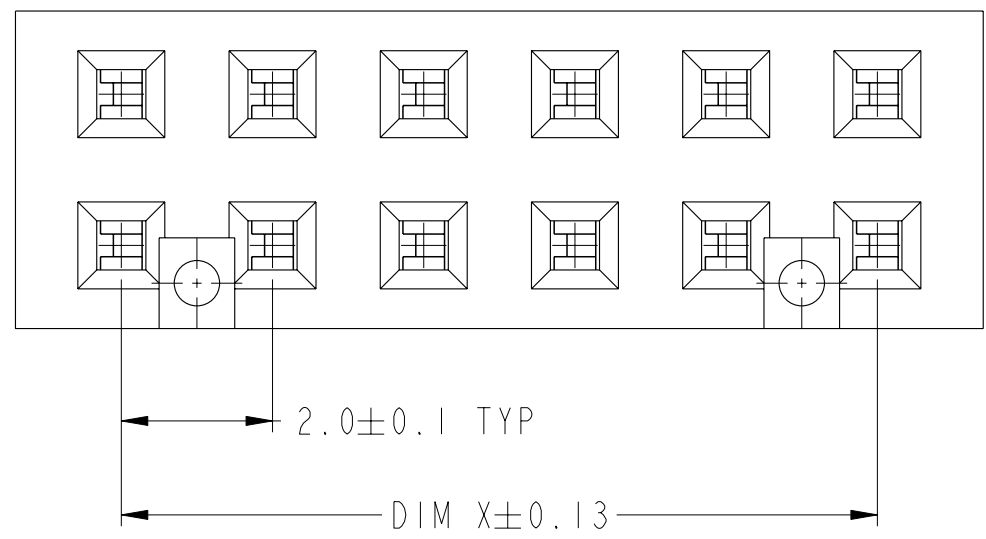


1

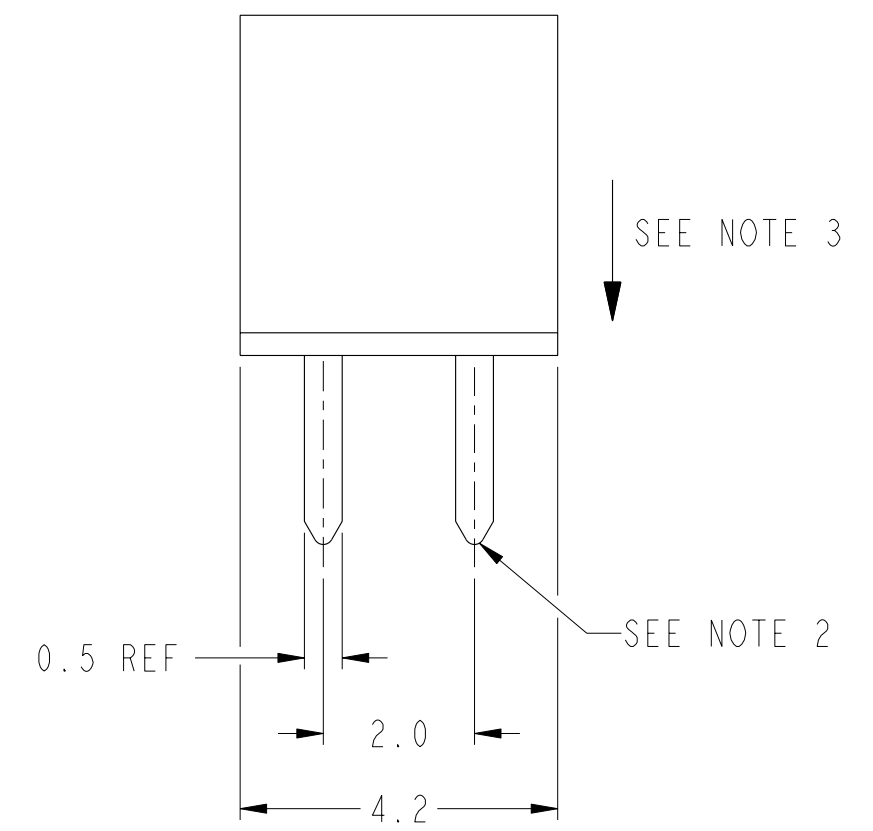
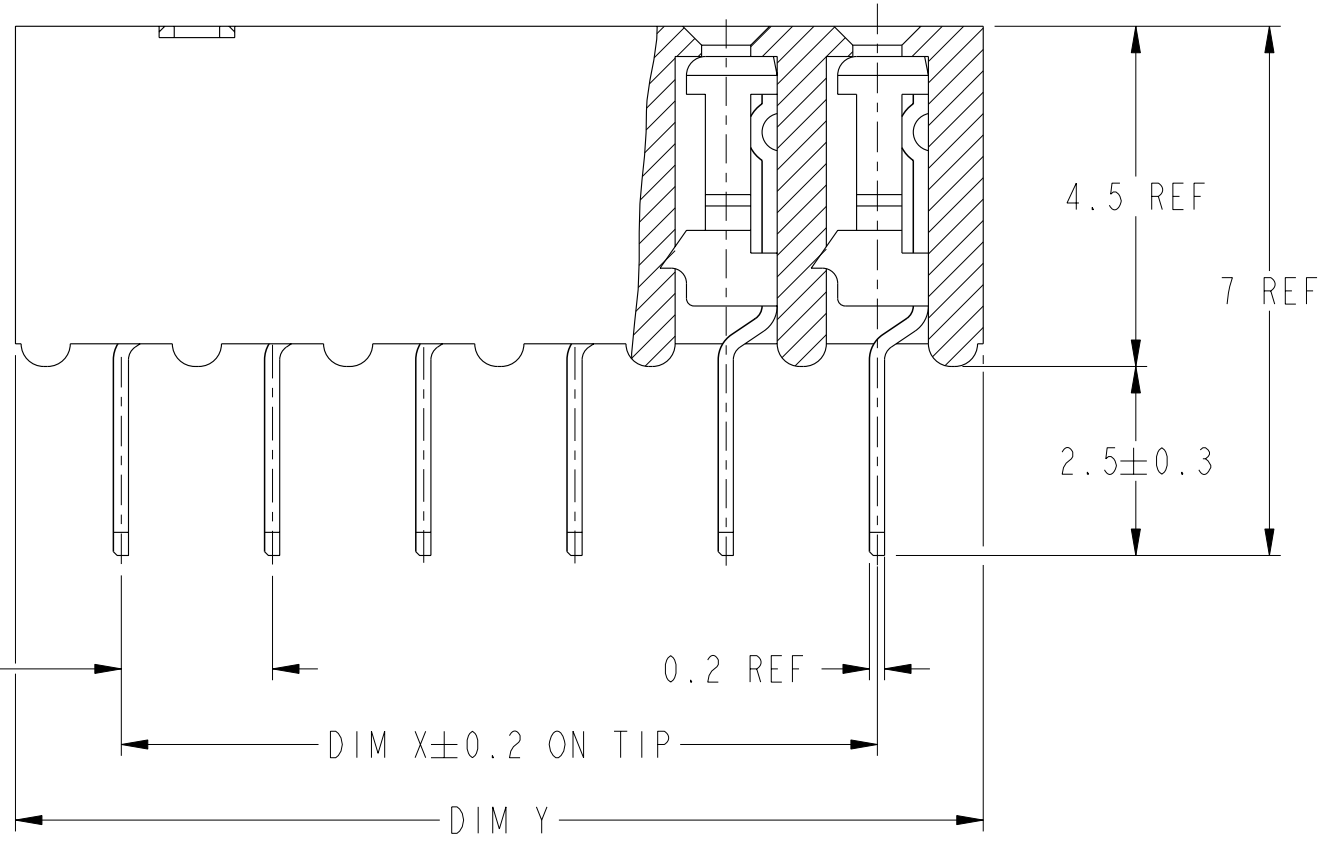
2

3

4



PC BOARD THK : 0.9 TO 1.3  
RECOMMENDED MOUNTING HOLE LAYOUT



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www.fciconnect.com		surface - ✓ ISO 1302	tolerance std ISO 406 ISO 1101	projection MM
TOLERANCES UNLESS OTHERWISE SPECIFIED				
Dr	JANET	2000-05-30	ANGULAR	x.X ±-
Eng	JPEH	2000-06-01	LINEAR	x.XX ±0.25
Chr	KH LEE	2010-01-20	0° ±°	x.XXX ±-
Appr	JOEY NG	2010-01-20	Product family	size A3 Scale 10:1
-				ECN S10-0205
-				Spec ref -
FCI			title MINITEK II VCC (HTP)	Rev. F
-			dwg no 87173	
-			CUSTOMER	sheet 1 of 2

rev	ecn no	dr	date
A	S0399	SET	1990-01-16
B	S10029	MLC	1991-01-31
C	S00100	SCT	2000-05-30
D	S05-0064	KBM	2005-03-01
E	S06-0243	KHL	2006-07-20
F	S10-0205	AK	2010-01-20
-	-	-	-

REV E - 2006-03-28

1

2

3

PDM: Rev:F

STATUS: Released

Printed: Nov 04, 2010

PRODUCT NO SEE NOTE 5	POS	DIM X	DIM Y
87173-X02	2 X 1	—OBSOLETE—	
-X04	2 X 2	2	4.8
-X06	2 X 3	4	6.8
-X08	2 X 4	6	8.8
-X10	2 X 5	8	10.8
-X12	2 X 6	10	12.8
-X14	2 X 7	12	14.8
-X16	2 X 8	14	16.8
-X18	2 X 9	16	18.8
-X20	2 X 10	18	20.8
-X22	2 X 11	20	22.8
-X24	2 X 12	22	24.8
-X26	2 X 13	24	26.8
-X28	2 X 14	26	28.8
-X30	2 X 15	28	30.8
-X32	2 X 16	30	32.8
-X34	2 X 17	32	34.8
-X36	2 X 18	34	36.8
-X38	2 X 19	36	38.8
-X40	2 X 20	38	40.8
-X42	2 X 21	40	42.8
-X44	2 X 22	42	44.8
-X46	2 X 23	44	46.8
-X48	2 X 24	46	48.8
-X50	2 X 25	48	50.8

CONTACT AREA PLATING	DESCRIPTION
0	0.2µm Au
1	0.76µm Au
2	UNASSIGNED
3	0.38µm Au
4	UNASSIGNED
5	UNASSIGNED
6	UNASSIGNED

**NOTES:**

- MATERIAL  
BODY : GLASS FILLED PCT UL 94V-0 BEIGE  
TERMINAL: PHOSPHOR BRONZE
- CUT SURFACE IS UNPLATED
- TERMINAL RETENTION FORCE 0.5 Kg MIN
- TOLERANCE UNLESS OTHERWISE NOTED ±0.25
- PRODUCT DESCRIPTION CODE:  
XXXXX-XXXLF  
  - LEAD FREE (SEE NOTES 6 & 9)
  - TOTAL POSITIONS
  - CONTACT AREA PLATING
  - BASE NUMBER
- SOLDERTAIL PLATING:  
a) SOLDERTAIL OF 87173-XXX IS TIN/LEAD PLATED.  
b) SOLDERTAIL OF 87173-XXXLF IS 100% MATTE TIN PLATED.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- A SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.

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www.fciconnect.com		surface <input checked="" type="checkbox"/> ISO 1302	tolerance std ISO 406 ISO 1101	projection	MM
TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	JANET	2000-05-30	ANGULAR	x.x ±°	size A3
Eng	JPEH	2000-06-01	LINEAR	x.xx ±0.25	Scale 10:1
Chr	KH LEE	2010-01-20	0° ±°	x.xxx ±°	ECN S10-0205
Appr	JOEY NG	2010-01-20	Product family	-	Spec ref -
		MINITEK II VCC (HTP)		dwg no 87173	Rev. F
-		catalog no	-	CUSTOMER	sheet 2 of 2